

ABSTRACT OF THE DISCLOSURE

An image sensor package includes plural lower metal sheets, plural upper metal sheets stacked on the lower metal sheets, and an encapsulant for encapsulating the lower and upper metal sheets. Wherein the upper metal sheets are shorter than that of the lower metal sheets, so the upper surface of the lower metal sheets are exposed from the encapsulant. A photosensitive chip arranged within the chamber, plural wires are for electrically connecting the chip to the upper surfaces of the lower metal sheets, and a transparent layer arranged on the frame layer to cover the chip.